



November 15, 2017

Intevac to Participate in the 6th Annual NYC Investor Summit 2017

SANTA CLARA, Calif.--(BUSINESS WIRE)-- Intevac, Inc. (Nasdaq: IVAC), today announced that company management is scheduled to participate in the 6th Annual NYC Investor Summit 2017, being held December 6, 2017 at Le Parker Méridien Hotel, New York City.

The presentation material utilized during the NYC Summit will be made accessible on the investor page of the company's website at www.intevac.com.

About the 6th Annual NYC Summit

The NYC Summit is hosted by executive management from participating companies and will feature a "round-robin" format consisting of small group meetings, each 30 minutes in duration. During the event, investors and analysts will have the opportunity to meet with up to 10 of the 15 management teams during the 30-minute group meeting sessions, as well as opportunities to meet with additional management teams during the breakfast and lunch networking sessions.

The 15 management teams collectively hosting the 2017 NYC Summit include: Aehr Test (AEHR), Axcelis (ACLS), BE Semiconductor Industries (BESI.AS), Brooks (BRKS), Camtek (CAMT), Cohu (COHU), Electro Scientific (ESIO), FormFactor (FORM), Ichor Systems (ICHR), Intermolecular (IMI), inTEST (INTT), Intevac (IVAC), Kulicke & Soffa (KLIC), Nanometrics (NANO), and Rudolph Technologies (RTEC). Cowen is sponsoring the networking luncheon.

The NYC Investor Summit is by invitation only and is open to accredited investors and publishing research analysts. As space is limited, please RSVP early. Hosts reserve the right to limit attendance as necessary. Last day for registration is November 27, 2017.

RSVP Contacts for 6th Annual NYC Summit 2017

To RSVP for the NYC Summit, please contact either of the Summit's co-chairs.

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About Intevac

Intevac was founded in 1991 and has two businesses: Thin-film Equipment and Photonics.

In our Thin-film Equipment business, we are a leader in the design and development of high-productivity, thin-film processing systems. Our production-proven platforms are designed for high-volume manufacturing of substrates with precise thin film properties, such as the hard drive media, display cover panel, and solar photovoltaic markets we serve currently.

In our Photonics business, we are a recognized leading developer of advanced high-sensitivity digital sensors, cameras and systems that primarily serve the defense industry. We are the provider of integrated digital imaging systems for most U.S. military night vision programs.

For more information call 408-986-9888, or visit the Company's website at www.intevac.com.

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Source: Intevac, Inc.

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